



Product Change Notification - KSRA-20QCEH898

Date:
15 Aug 2019

Product Category:
8-bit Microcontrollers

Affected CPNs:
 

Notification subject:
CCB 3074 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond in selected products of the 200K wafer technology available in 8L DFN (2x3x0.9mm) package at NSEB assembly site

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond in selected products of the 200K wafer technology available in 8L DFN (2x3x0.9mm) package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8200T or 8600 die attach material, G770HCD or G700LTD molding compound material and EFTEC-64T lead frame material

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach material, G700LTD molding compound material and C194 lead frame material

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	UTAC Thai Limited LTD. (NSEB)		UTAC Thai Limited LTD. (NSEB)
Wire material	Au Wire		CuPdAu Wire
Die attach material	8200T	8600	8600
Molding compound material	G770HCD	G700LTD	G700LTD
Lead frame material	EFTEC-64T		C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

May 24, 2018 (date code: 1821)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts



Time Table Summary:

	August 2017					-->	April 2018					May 2018				
Workweek	31	32	33	34	35		14	15	16	17	18	19	20	21	22	
Initial PCN Issue Date					X											
Qual Report Availability										X						
Final PCN Issue Date										X						
Estimated Implementation Date														X		

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Revision History:

August 31, 2017: Issued initial notification with PCN No. [KSRA-27FAPU261](#).

April 24, 2018: Issued final notification. Attached the Qualification Report. Provided estimated first ship date on May 24, 2018.

August 15, 2019: Re-issued final notification to specify the package size (2x3x0.9mm) in the subject and description of change and update the affected CPN list.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-20QCEH898_Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PIC10F320-E/MC
PIC10F320-I/MC
PIC10F320T-I/MC
PIC10F322-E/MC
PIC10F322-I/MC
PIC10F322T-I/MC
PIC10LF320-E/MC
PIC10LF320-I/MC
PIC10LF320T-I/MC
PIC10LF322-E/MC
PIC10LF322-I/MC
PIC10LF322T-I/MC
PIC12F1501-E/MC
PIC12F1501-I/MC
PIC12F1501T-I/MC
PIC12LF1501-E/MC
PIC12LF1501-I/MC
PIC12LF1501-I/MC020
PIC12LF1501T-E/MC
PIC12LF1501T-I/MC
PIC12LF1501T-I/MC020
PIC12LF1501T-I/MC021